Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	46	(seed adj layer) near10 (ink$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/02 12:32
S165	2095	((plated or plating) with copper with seed)	US-PGPUB; USPAT	OR	OFF	2005/12/01 17:22
S166	1894	((plated or plating) near12 copper near12 seed)	US-PGPUB; USPAT	OR	OFF	2005/12/01 16:49
S167	1828	((plated or plating) near10 copper near10 seed)	US-PGPUB; USPAT	OR	OFF	2005/12/01 16:51
S168	180	((plated or plating) near10 copper near10 seed).clm.	US-PGPUB; USPAT	OR	OFF	2005/12/01 16:50
S169	326	((plated or plating) near10 copper near10 seed) and (circuit adj board)	US-PGPUB; USPAT	OR	OFF	2005/12/01 16:51
S170	14	((plated or plating) with copper with seed) and (conduct$4 adj ink$1)	US-PGPUB; USPAT	OR	OFF	2005/12/01 17:33
S171	4	(electroplat$3 with seed) with (conduct$4 adj ink$1)	US-PGPUB; USPAT	OR	OFF	2005/12/01 17:34
S172	4	(electroplat$3 with seed) with (conduct$4 adj ink$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:35
S173	15	(electroplat$3 or plat$3) and (seed near10 (conduct$4 adj ink$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:36
S174	666	(electroplat$3 or plat$3) and (seed near10 silver)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:37
S175	14	(seed adj layer) near10 (conduct$4 adj ink$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/02 12:32